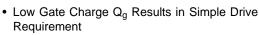


JCS1N60V-VB Datasheet N-Channel 650V (D-S) Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	650				
$R_{DS(on)}\left(\Omega\right)$	V _{GS} = 10 V 4				
Q _g (Max.) (nC)	11				
Q _{gs} (nC)	2.3				
Q _{gd} (nC)	5.2				
Configuration	Single				

FEATURES

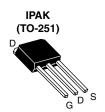


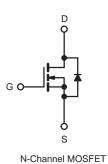


• Improved Gate, Avalanche and Dynamic dV/dt Ruggedness



- Fully Characterized Capacitance and Avalanche Voltage and Current
- Compliant to RoHS directive 2002/95/EC





PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	650	V	
Gate-Source Voltage			V_{GS}	± 30	V	
Continuous Drain Currente	\/ at 10 \/	T _C = 25 °C	1-	2.0		
Continuous Drain Current	V_{GS} at 10 V $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 100 ^{\circ}\text{C}$		I _D	1.28	Α	
Pulsed Drain Current ^a			I _{DM}	8		
Linear Derating Factor				0.48	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	165	mJ	
Repetitive Avalanche Current ^a			I _{AR}	2	Α	
Repetitive Avalanche Energy ^a			E _{AR}	6	mJ	
aximum Power Dissipation $T_C = 25 ^{\circ}C$		25 °C	P_{D}	45	W	
Peak Diode Recovery dV/dtc			dV/dt	2.8	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	- °C	
Soldering Recommendations (Peak Temperature) ^d for 10 s				300		
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. Starting T $_J$ = 25 °C, L = 24 mH, R $_G$ = 25 Ω , I $_{AS}$ = 3.2 A (see fig. 12). c. I $_{SD}$ ≤ 3.2 A, dl/dt ≤ 90 A/ μ s, V $_{DD}$ ≤ V $_{DS}$, T $_J$ ≤ 150 °C.

- d. 1.6 mm from case.
- e. Drain current limited by maximum junction temperature.



THERMAL RESISTANCE RATINGS						
PARAMETER SYMBOL TYP. MAX. UNI						
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W		
Maximum Junction-to-Case (Drain)	R _{thJC}	=	2.1	C/VV		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA ^d	-	670	-	mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	,	V _{GS} = ± 30 V	ı	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}		= 650 V, V _{GS} = 0 V V, V _{GS} = 0 V, T _J = 125 °C	-	-	25 250	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 1 A b	-	4.0	-	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 50 V, I _D = 1 A	3.9	-	-	S
Dynamic		1					1
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,	-	417	-	
Output Capacitance	C _{oss}		$V_{DS} = 25 \text{ V},$	-	45	-	
Reverse Transfer Capacitance	C _{rss}	f = 1	f = 1.0 MHz, see fig. 5		5	-	
Output Capacitance	C	$V_{DS} = 1.0 \text{ V}, f = 1.0 \text{ MHz}$ $V_{GS} = 0 \text{ V}$ $V_{DS} = 520 \text{ V}, f = 1.0 \text{ MHz}$	V _{DS} = 1.0 V, f = 1.0 MHz	ı	912	-	pF
Output Capacitance	C _{oss}		ı	26			
Effective Output Capacitance	Coss eff.		V _{DS} = 0 V to 520 V ^c		42	-	
Total Gate Charge	Q_g		V _{GS} = 10 V		-	11	nC
Gate-Source Charge	Q_{gs}	V _{GS} = 10 V			-	2.3	
Gate-Drain Charge	Q_{gd}				-	5.2	
Turn-On Delay Time	t _{d(on)}		1		14	-	†
Rise Time	t _r		= 325 V, I _D = 1.2A	i	20	-	1
Turn-Off Delay Time	t _{d(off)}	$R_{G} =$	$R_G = 9.1 \Omega, R_D = 62 \Omega,$ see fig. 10^b		34	-	ns -
Fall Time	t _f	1		-	18	-	
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	8	
Body Diode Voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 3.2 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	T. = 25 °C L	T 25 00 1 2 2 A 21/24 400 A / 25		180	230	ns
Body Diode Reverse Recovery Charge	Qrr	$T_J = 25 \text{ °C}, I_F = 3.2 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}^b$		-	2.1	3.2	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_{S} and L_{D})					L _D)

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %. c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .
- d. t = 60 s, f = 60 Hz.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

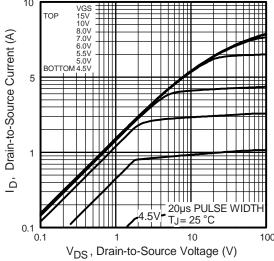


Fig. 1 - Typical Output Characteristics

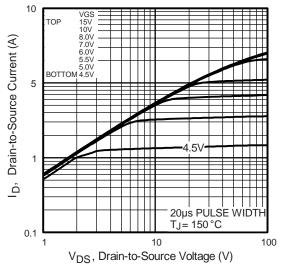


Fig. 2 - Typical Output Characteristics

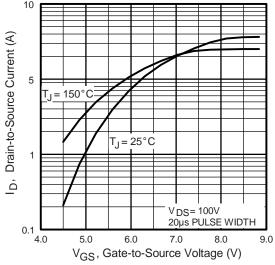


Fig. 3 - Typical Transfer Characteristics

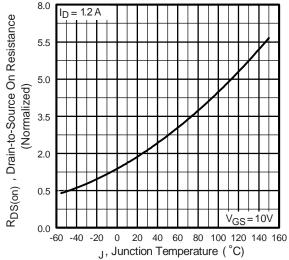


Fig. 4 - Normalized On-Resistance vs. Temperature



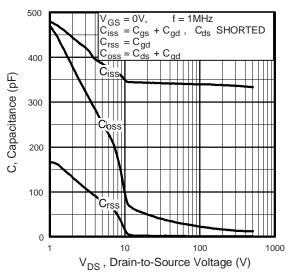


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

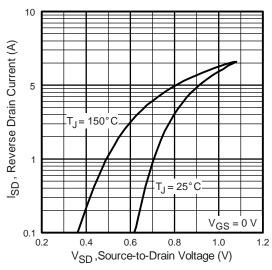


Fig. 7 - Typical Source-Drain Diode Forward Voltage

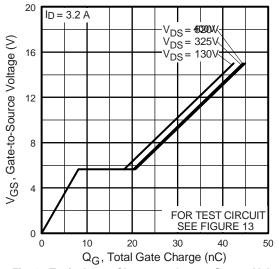


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

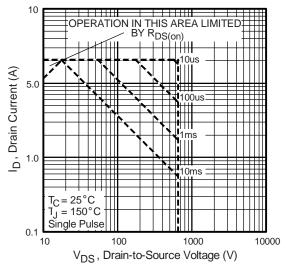


Fig. 8 - Maximum Safe Operating Area



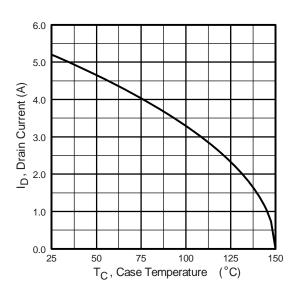


Fig. 9 - Maximum Drain Current vs. Case Temperature

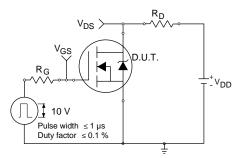


Fig. 10a - Switching Time Test Circuit

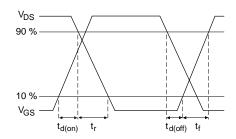


Fig. 10b - Switching Time Waveforms

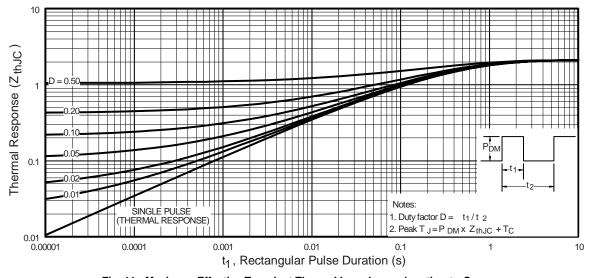


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

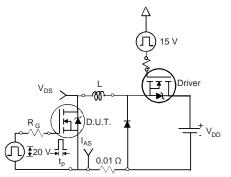


Fig. 12a - Unclamped Inductive Test Circuit

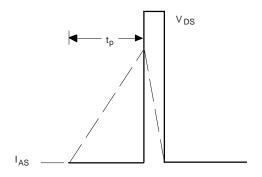


Fig. 12b - Unclamped Inductive Waveforms



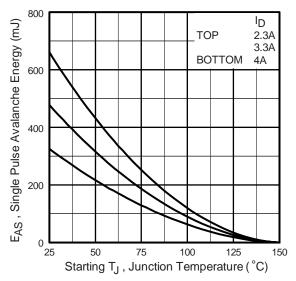


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

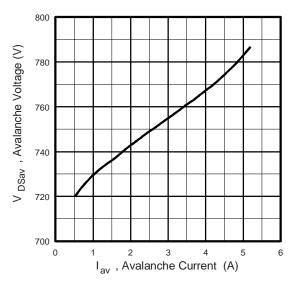


Fig. 12d - Typical Drain-to Source Voltage vs. Avalanche Current

6

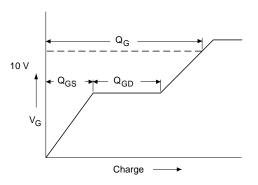


Fig. 13a - Basic Gate Charge Waveform

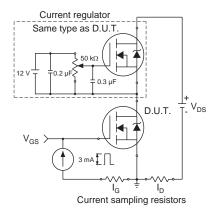
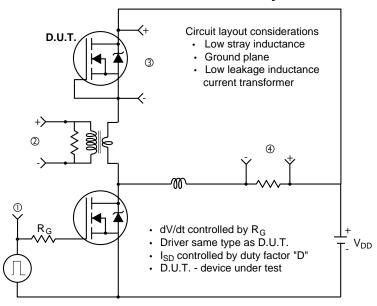
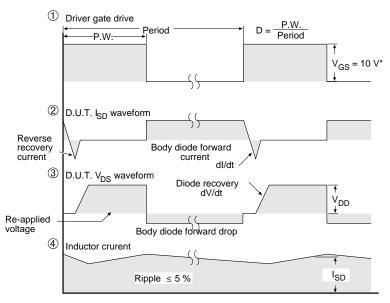


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



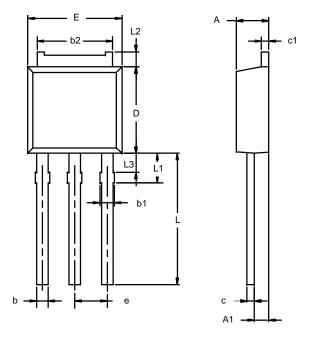


* $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel



TO-251AA



Note:	Dimension	L3 is fo	or reference	only.
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	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	



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